

CLAIMS

1. A method of peeling a semiconductor chip, comprising the steps of:

5 peeling a semiconductor chip adhered to a
tape from said tape by a peeling device including a
plurality of annular contact members arranged one after
another from the outside to the inside, wherein the
plurality of annular contact members are operated so that
the semiconductor chip is successively peeled off from
10 the tape from an outer circumferential portion thereof
toward a central portion thereof.

15 2. The method of peeling a semiconductor chip
according to claim 1, wherein the plurality of annular
contact members are simultaneously moved, and then, the
outermost annular contact member in the plurality of
annular contact members is stopped and the remaining
annular contact members are further moved simultaneously.

20 3. A device for peeling a semiconductor chip
adhered to a tape off from said tape, comprising:

25 a plurality of annular contact members
arranged one after another from the outside to the
inside; and

30 an operation device for operating the
plurality of annular contact members so that the
semiconductor chip is successively peeled, from the tape,
from an outer circumferential portion thereof to a
central portion thereof.

35 4. The device for peeling a semiconductor chip
according to claim 3, wherein the operation device
includes a cam for operating the plurality of annular
contact members.

5. The device for peeling a semiconductor chip
according to claim 3, further comprising a frame defining
a vacuum chamber therein, a top plate arranged on said
frame and having an opening, and a suction device
arranged above said frame, said annular contact members
being arranged in said frame.